

1A, 40V - 200V Schottky Barrier Surface Mount Rectifier

FEATURES

- Ideal for automated placement
- Compact package size, profile <0.85mm
- Ultra low leakage current
- High surge current capability
- Low power loss, high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- DC to DC converter

MECHANICAL DATA

• Case: SOD-123HE

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

• Polarity: Indicated by cathode band

• Weight: 0.021g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	TINU			
I _F	1	Α			
V_{RRM}	40 - 200	V			
I _{FSM}	30	Α			
T_{JMAX}	150	°C			
Package	SOD-123HE				
Configuration	Single die				





SOD-123HE



PARAMETER	SYMBOL	SS1H4	SS1H6	SS1H10	SS1H15	SS1H20	
		LS	LS	LS	LS	LS	UNIT
Marking code on the device		1H4LS	1H6LS	1H10LS	1H15LS	1H20LS	
Repetitive peak reverse voltage	V_{RRM}	40	60	100	150	200	V
Reverse voltage, total rms value	V _{R(RMS)}	28	42	70	105	140	V
Forward current	I _F			1			Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30				А	
Junction temperature	T_J	- 55 to +150				°C	
Storage temperature	T _{STG}			- 55 to +150)		°C

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	20	°C/W		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	72	°C/W		

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	SS1H4LS		V _F	-	0.65	V
	SS1H6LS			-	0.70	V
	SS1H10LS			-	0.80	V
	SS1H15LS SS1H20LS			-	0.85	V
Reverse current @ rated V _R ⁽²⁾	SS1H4LS	T _J = 25°C	I _R	-	1.0	μA
	SS1H6LS	T _J = 125°C		-	0.3	mA
	SS1H10LS SS1H15LS	T _J = 25°C		-	1.0	μA
		T _J = 125°C		-	0.2	mA
	SS1H20LS	T _J = 25°C		-	1.0	μA
	3311120L3	T _J = 125°C		-	0.1	mA

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
SS1HxLS	SOD-123HE	10,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 40V(SS1H4LS) to 200V(SS1H20LS)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

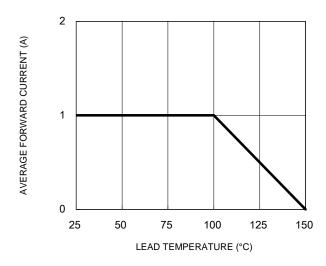


Fig.3 Typical Reverse Characteristics

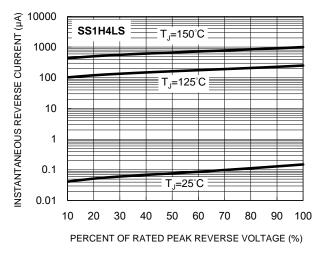


Fig.5 Typical Reverse Characteristics

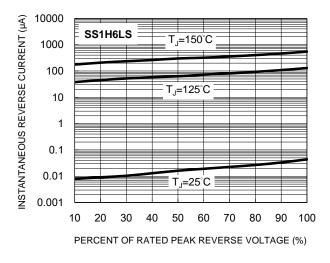


Fig.2 Typical Junction Capacitance

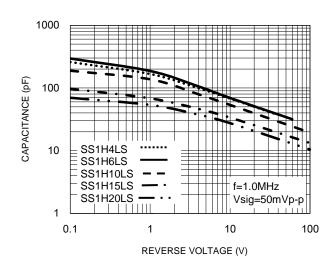


Fig.4 Typical Forward Characteristics

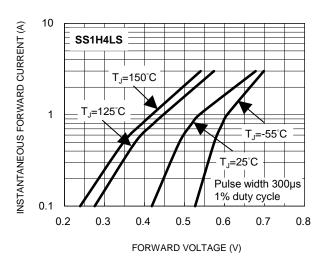
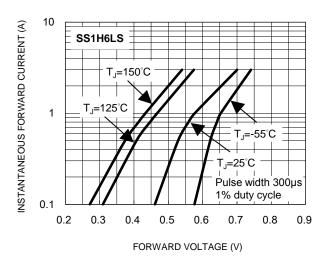


Fig.6 Typical Forward Characteristics



3 Version: C2208



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.7 Typical Reverse Characteristics

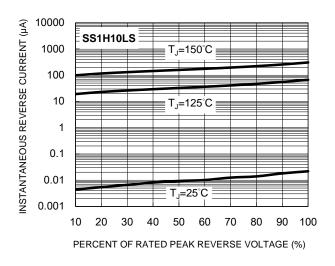


Fig.9 Typical Reverse Characteristics

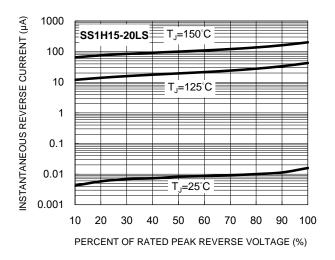


Fig.8 Typical Forward Characteristics

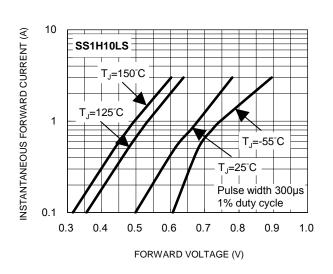


Fig.10 Typical Forward Characteristics

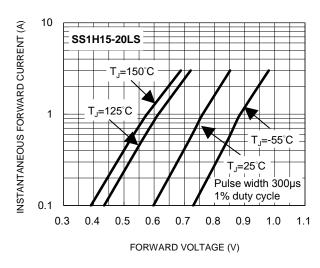
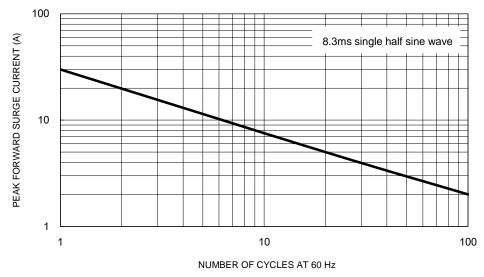


Fig.11 Maximum Non-Repetitive Forward Surge Current

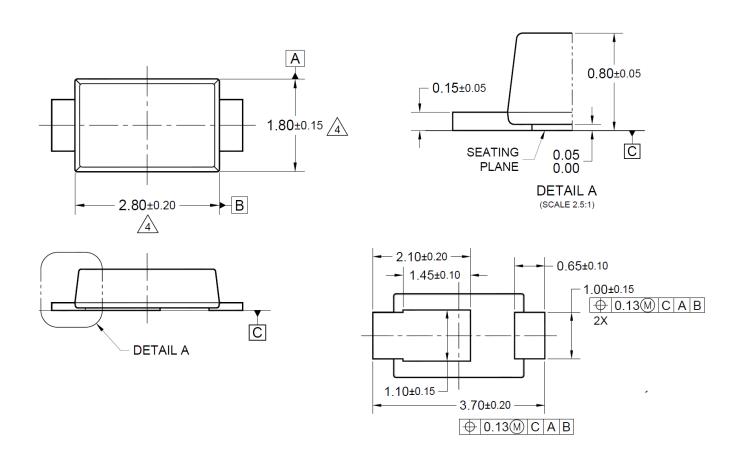


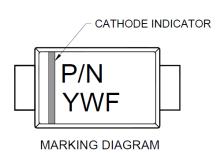
Version: C2208



PACKAGE OUTLINE DIMENSIONS

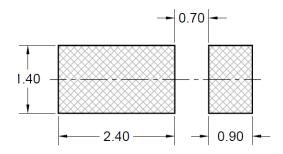
SOD-123HE





P/N = MARKING CODE YW = DATE CODE

= FACTORY CODE



SUGGESTED PAD LAYOUT

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- 3. THERE IS NO EXISTING INDUSTRY STANDARD FOR THIS PACKAGE.

4\ MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.

5. DWG NO. REF: HQ2SD07-SOD123HE-038 REV A.

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